METHOD FOR FABRICATING A DUAL DAMASCENE STRUCTURE

Abstract of Disclosure

A method for fabricating a dual damascene structure contains providing a substrate having a conductive layer, an etching stop layer, a dielectric layer, and a photoresist layer thereon, performing an etching process to remove a portion of the dielectric layer through a via pattern of the photoresist layer for forming a via structure in the dielectric layer, providing CO-containing gas to perform an ash process, filling GFP materials into the via structure, forming a photoresist layer with a trench pattern on the substrate, etching the dielectric layer through the trench pattern to form a trench structure in the dielectric layer, above the via structure, and removing the etching stop layer exposed in the via structure.

Figure 15